## PATENT APPLICATION

## **RESPONSE UNDER 37 CFR §1.116 EXPEDITED PROCEDURE TECHNOLOGY CENTER ART UNIT 1792**

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Shigehiro NISHINO et al.

Group Art Unit: 1792

Application No.: 10/520,141

Examiner:

M. SONG

Filed: September 1, 2005

Docket No.: 122261

LARGE-DIAMETER SIC WAFER AND MANUFACTURING METHOD THEREOF For:

## **AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116**

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In reply to the November 26, 2008 Office Action, please consider the following:

Amendments to the Claims as reflected in the listing of claims; and

Remarks.